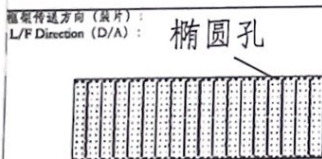
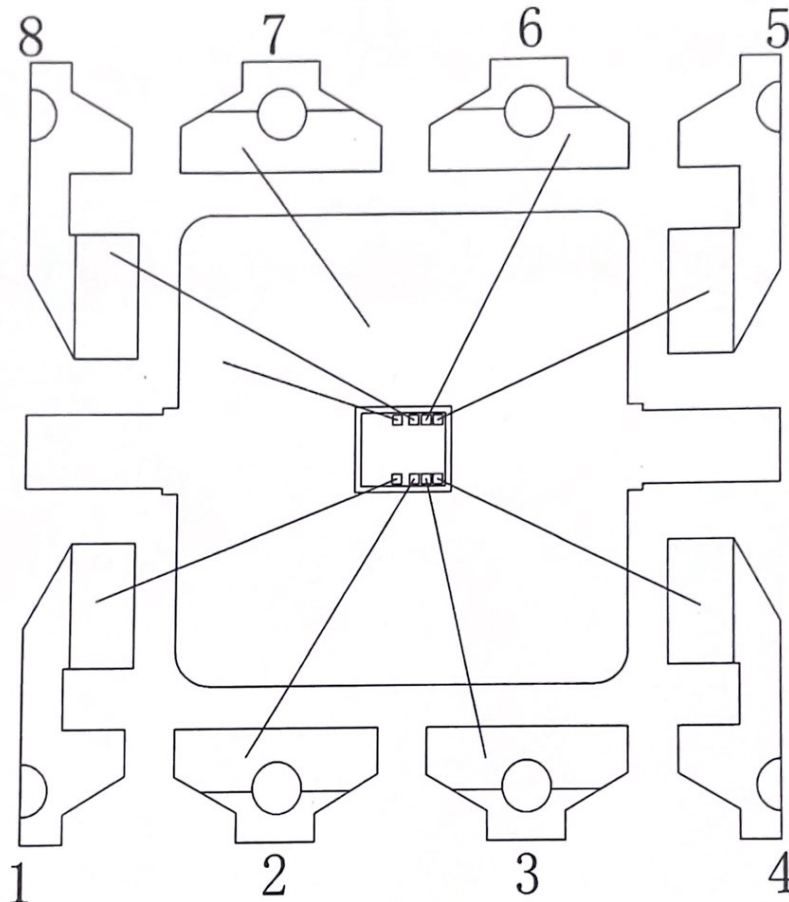


 池州华宇电子科技股份有限公司 CHI ZHOU HISEEMI ELECTRONICS TECHNOLOGY CO.,LTD				客户代码 Customer No.	008	线号 Drawing No.	HY-PX-008-732 A	
焊线图纸 Bonding Diagram				产品名称 Product Type	HS6107		封装外型 PKG Type	SOP8L (12R)
焊线种类 Wire Type	焊线直径(um) Wire Diameter	焊线根数 NO. of wire	焊线总长(um) Total wire length	最长线长(um) Longest wire length	最短线长(um) Shortest wire length	焊线材料型号(绿色环保) Compound Type (Green)	LF载带尺寸 LF Pad Size	
合金丝 Ag	20	9	14990	1749	935	首选(Preferred): CEL-1702HF 备选(Optional): EME-G630AY	SOP8L-12R (90*90mil) 2286*2286(um ²)	
客户图号 Customer drawing NO.								



实物图:
Chip photo:

特殊说明 Special Instructions:

DB注意:
1、芯片居中放置;

注意: 基岛全镀银

说明 Instructions	贴片胶类型 Epoxy type	芯片名称 Die name	芯片尺寸 Die Size	最小焊盘尺寸 Min BPN (um ²)	最小焊盘间距 Min BPP(um)	铝垫厚度(um) Pad Thickness	焊盘下是否有电路 Circuit under Pad	贴片线宽度 Street line (um)	晶圆尺寸 Wafer Size	是否过 100%R If how R?	载带厚度 (um) Wafer Thickness
A芯: DIE A	导电胶 (conductive) S210	HS5156	429.4*353.4(um ²) 16.89*13.91(mil ²)	48.45*48.45	58	0.8	是/Yes	60	8	否/NO	300
B芯: DIE B											
C芯: DIE C											

制图日期 Create Date	2024/2/4	生效日期 Effective Date		客户确认签字/盖章: Customer Signature
编制 Prepared by	1772 Long 2-4	审核 Checked by	3830 2024.2.4	批准 Approved by

*温馨提示: 因该方产品下机生产的唯一依据, 请认真确认, 我司将根据您签字的图纸生产, 如因疏忽造成生产不可估量损失, 谢谢!
*warm tips: the drawing is the only basis for the production of the product. Please confirm it carefully. Our company will produce the drawings according to the drawings you have signed back, such as drawing mistakes, which will produce inevitable loss. Thank you